

Wafer Flatness

Specifications



Global Flatness Specifications

Bow	Distance between the surface and the best fit plane at the center of an unclamped wafer.	Warp	Sum of the maximum positive and negative deviations from the best fit plane (wafer unclamped).
TTV Total Thickness Variation	Difference between the maximum and minimum values of the wafer thickness (wafer clamped).	TIR Total Indicated Reading	Sum of the maximum positive and negative deviations from the best fit plane (wafer clamped).
SRAD Spherical Reference Measurement ('Radius of Curvature')	The length of the radius in metres for the best fit sphere. The flatter the surface, the larger the best fit sphere.		

Local Flatness Specifications

LFPD Local Focal Plane Deviation	Maximum distance between the wafer surface and best fit plane (above or below), for a given area (wafer unclamped).	LTV Local Thickness Variation	Difference between the maximum and minimum values of wafer thickness for a given area (wafer clamped).

